



FQB5N50C

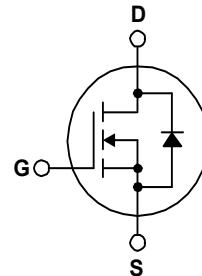
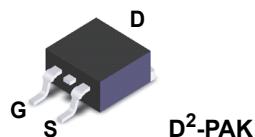
N-Channel QFET® MOSFET 500 V, 5 A, 1.4 Ω

Features

- 5 A, 500 V, $R_{DS(on)}$ = 1.4 Ω (Max.) @ $V_{GS} = 10$ V, $I_D = 2.5$ A
- Low Gate Charge (Typ. 18 nC)
- Low C_{rss} (Typ. 15 pF)
- 100% Avalanche Tested
- RoHS Compliant

Description

This N-Channel enhancement mode power MOSFET is produced using Fairchild Semiconductor's proprietary planar stripe and DMOS technology. This advanced MOSFET technology has been especially tailored to reduce on-state resistance, and to provide superior switching performance and high avalanche energy strength. These devices are suitable for switched mode power supplies, active power factor correction (PFC), and electronic lamp ballasts.



Absolute Maximum Ratings $T_C = 25^\circ\text{C}$ unless otherwise noted.

Symbol	Parameter	FQB5N50CTM	Unit
V_{DSS}	Drain-Source Voltage	500	V
I_D	Drain Current - Continuous ($T_C = 25^\circ\text{C}$)	5	A
	- Continuous ($T_C = 100^\circ\text{C}$)	2.9	A
I_{DM}	Drain Current - Pulsed	(Note 1) 20	A
V_{GSS}	Gate-Source Voltage	± 30	V
E_{AS}	Single Pulsed Avalanche Energy	(Note 2) 300	mJ
I_{AR}	Avalanche Current	(Note 1) 5	A
E_{AR}	Repetitive Avalanche Energy	(Note 1) 7.3	mJ
dv/dt	Peak Diode Recovery dv/dt	(Note 3) 4.5	V/ns
P_D	Power Dissipation ($T_C = 25^\circ\text{C}$)	73	W
	- Derate above 25°C	0.58	W/ $^\circ\text{C}$
T_J, T_{STG}	Operating and Storage Temperature Range	-55 to +150	$^\circ\text{C}$
T_L	Maximum lead temperature for soldering purposes, 1/8" from case for 5 seconds	300	$^\circ\text{C}$

Thermal Characteristics

Symbol	Parameter	FQB5N50CTM	Unit
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case, Max.	1.71	$^\circ\text{C}/\text{W}$
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient, Max.	62.5	

Package Marking and Ordering Information

Device Marking	Device	Package	Reel Size	Tape Width	Quantity
FQB5N50C	FQB5N50CTM	D ² -PAK	330 mm	24 mm	800 units

Electrical Characteristics $T_C = 25^\circ\text{C}$ unless otherwise noted.

Symbol	Parameter	Test Conditions	Min	Typ	Max	Unit
Off Characteristics						
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{\text{GS}} = 0 \text{ V}$, $I_D = 250 \mu\text{A}$	500	--	--	V
$\Delta \text{BV}_{\text{DSS}} / \Delta T_J$	Breakdown Voltage Temperature Coefficient	$I_D = 250 \mu\text{A}$, Referenced to 25°C	--	0.5	--	$^\circ\text{C}$
I_{DSS}	Zero Gate Voltage Drain Current	$V_{\text{DS}} = 500 \text{ V}$, $V_{\text{GS}} = 0 \text{ V}$	--	--	1	μA
		$V_{\text{DS}} = 400 \text{ V}$, $T_C = 125^\circ\text{C}$	--	--	10	μA
I_{GSSF}	Gate-Body Leakage Current, Forward	$V_{\text{GS}} = 30 \text{ V}$, $V_{\text{DS}} = 0 \text{ V}$	--	--	100	nA
I_{GSSR}	Gate-Body Leakage Current, Reverse	$V_{\text{GS}} = -30 \text{ V}$, $V_{\text{DS}} = 0 \text{ V}$	--	--	-100	nA
On Characteristics						
$V_{\text{GS(th)}}$	Gate Threshold Voltage	$V_{\text{DS}} = V_{\text{GS}}$, $I_D = 250 \mu\text{A}$	2.0	--	4.0	V
$R_{\text{DS(on)}}$	Static Drain-Source On-Resistance	$V_{\text{GS}} = 10 \text{ V}$, $I_D = 2.5\text{A}$	--	1.14	1.4	Ω
g_{FS}	Forward Transconductance	$V_{\text{DS}} = 40 \text{ V}$, $I_D = 2.5\text{A}$	--	5.2	--	S
Dynamic Characteristics						
C_{iss}	Input Capacitance	$V_{\text{DS}} = 25 \text{ V}$, $V_{\text{GS}} = 0 \text{ V}$, $f = 1.0 \text{ MHz}$	--	480	625	pF
C_{oss}	Output Capacitance		--	80	105	pF
C_{rss}	Reverse Transfer Capacitance		--	15	20	pF
Switching Characteristics						
$t_{\text{d(on)}}$	Turn-On Delay Time	$V_{\text{DD}} = 250 \text{ V}$, $I_D = 5\text{A}$, $R_G = 25 \Omega$	--	12	35	ns
t_r	Turn-On Rise Time		--	46	100	ns
$t_{\text{d(off)}}$	Turn-Off Delay Time		--	50	110	ns
t_f	Turn-Off Fall Time		--	48	105	ns
Q_g	Total Gate Charge	$V_{\text{DS}} = 400 \text{ V}$, $I_D = 5\text{A}$, $V_{\text{GS}} = 10 \text{ V}$	--	18	24	nC
Q_{gs}	Gate-Source Charge		--	2.2	--	nC
Q_{gd}	Gate-Drain Charge		--	9.7	--	μC
Drain-Source Diode Characteristics and Maximum Ratings						
I_S	Maximum Continuous Drain-Source Diode Forward Current	--	--	5	A	
I_{SM}	Maximum Pulsed Drain-Source Diode Forward Current	--	--	20	A	
V_{SD}	Drain-Source Diode Forward Voltage	$V_{\text{GS}} = 0 \text{ V}$, $I_S = 5 \text{ A}$	--	--	1.4	V
t_{rr}	Reverse Recovery Time	$V_{\text{GS}} = 0 \text{ V}$, $I_S = 5 \text{ A}$, $dI_F / dt = 100 \text{ A}/\mu\text{s}$	--	263	--	ns
Q_{rr}	Reverse Recovery Charge		--	1.9	--	μC

NOTES:

1. Repetitive Rating : Pulse width limited by maximum junction temperature.
2. $L = 21.5 \text{ mH}$, $I_{AS} = 5 \text{ A}$, $V_{DD} = 50 \text{ V}$, $R_G = 25 \Omega$, starting $T_J = 25^\circ\text{C}$.
3. $I_{SD} \leq 5 \text{ A}$, $di/dt \leq 200 \text{ A}/\mu\text{s}$, $V_{DD} \leq \text{BV}_{\text{DSS}}$, starting $T_J = 25^\circ\text{C}$.
4. Essentially independent of operating temperature.

Typical Characteristics

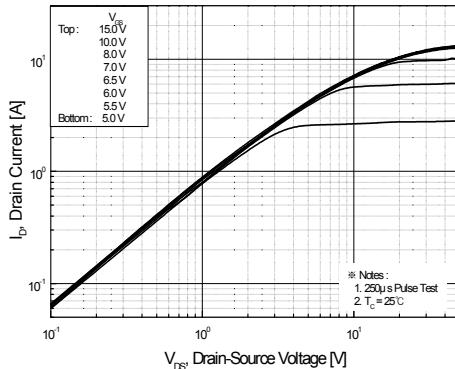


Figure 1. On-Region Characteristics

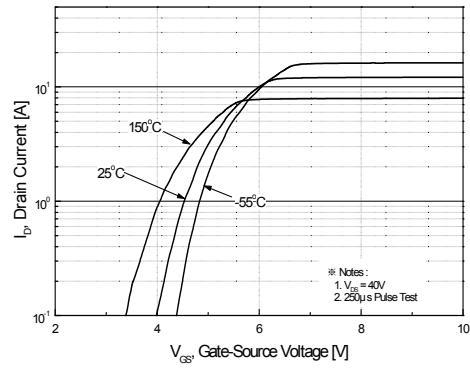


Figure 2. Transfer Characteristics

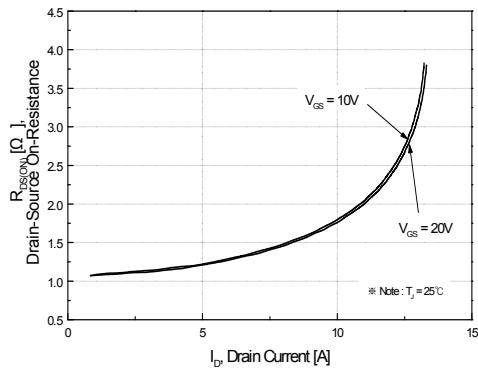


Figure 3. On-Resistance Variation vs. Drain Current and Gate Voltage

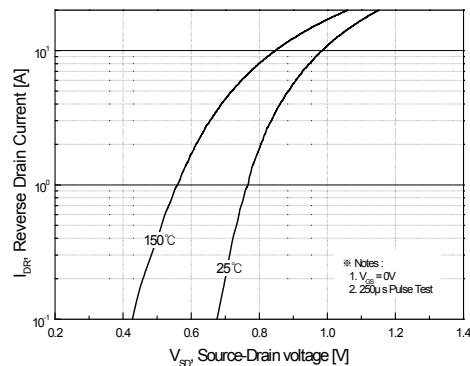


Figure 4. Body Diode Forward Voltage Variation with Source Current and Temperature

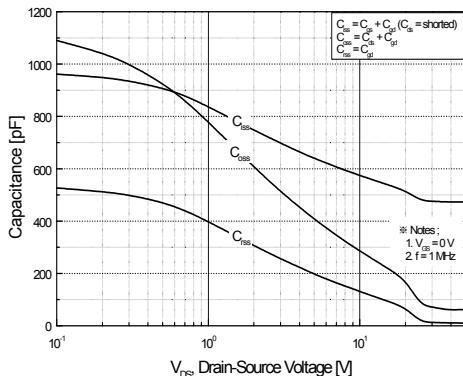


Figure 5. Capacitance Characteristics

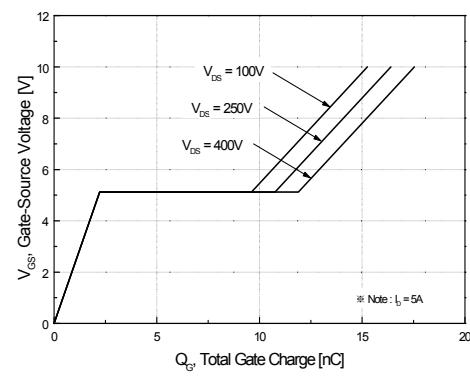


Figure 6. Gate Charge Characteristics